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## **Electromagnetic compatibility (EMC) –**

### **Part 4-33:**

### **Testing and measurement techniques – Measurement methods for high-power transient parameters**

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## CONTENTS

FOREWORD.....	4
INTRODUCTION .....	6
1 Scope.....	7
2 Normative references.....	7
3 Terms and definitions.....	8
4 Measurement of high-power transient responses .....	9
4.1 Overall measurement concepts and requirements.....	9
4.2 Representation of a measured response.....	11
4.3 Measurement equipment.....	12
4.4 Measurement procedures.....	27
5 Measurement of low frequency responses.....	27
6 Calibration procedures .....	28
6.1 Calibration of the entire measurement channel.....	28
6.2 Calibration of individual measurement channel components .....	31
6.3 Approximate calibration techniques.....	37
Annex A (normative) Methods of characterizing measured responses .....	40
Annex B (informative) Characteristics of measurement sensors.....	45
Annex C (normative) HPEM measurement procedures.....	59
Annex D (informative) Two-port representations of measurement chain components .....	62
Bibliography.....	69
Figure 1 – Illustration of a typical instrumentation chain for measuring high-power transient responses .....	10
Figure 2 – Illustration of a balanced sensor and cable connecting to an unbalanced (coaxial) line where $I_{out} + I_{in} = I_{in}$ .....	16
Figure 3 – Examples of some simple baluns [4b] .....	18
Figure 4 – A typical circuit for an in-line attenuator in the measurement chain.....	18
Figure 5 – Illustration of the typical attenuation of a nominal 20 dB attenuator for a 50-Ω system, as a function of frequency.....	19
Figure 6 – Typical circuit diagram for an in-line integrator.....	20
Figure 7 – Plot of the transfer function of the integrating circuit of Figure 6.....	20
Figure 8 – Illustration of the frequency dependent per-unit-length signal transmission of a standard coaxial cable, and a semi-rigid coaxial line.....	21
Figure 9 – Illustration of sensor cable routing in regions not containing EM fields.....	24
Figure 10 – Treatment of sensor cables when located in a region containing EM fields.....	25
Figure 11 – Conforming cables to local system shielding topology .....	26
Figure 12 – Correct and incorrect methods of cable routing.....	27
Figure 13 – The double-ended TEM Cell for providing a uniform field illumination for probe calibration .....	29
Figure 14 – Illustration of the single-ended TEM cell and associated equipment.....	30
Figure 15 – Dimensions of a small test fixture for probe calibration.....	30

Figure 16 – Electrical representation of a measurement chain, (a) with the E-field sensor represented by a general Thevenin circuit, and (b) the Norton equivalent circuit for the same sensor.....	31
Figure 17 – Example of a simple E-field probe.....	34
Figure 18 – Plot of the real and imaginary parts of the input impedance, $Z_i$ , for the E-field sensor of Figure 17.....	34
Figure 19 – Plot of the magnitude of the short-circuit current flowing in the sensor input for different angles of incidence, as computed by an antenna analysis code.....	35
Figure 20 – Plot of the magnitude of the effective height of the sensor for different angles of incidence.....	36
Figure 21 – High frequency equivalent circuit of an attenuator element.....	39
Figure A.1 – Illustration of various parameters used to characterize the pulse component of a transient response waveform $R(t)$ .....	41
Figure A.2 – Illustration of an oscillatory waveform frequently encountered in high-power transient EM measurements.....	41
Figure A.3 – Example of the calculated spectral magnitude of the waveform of Figure A.2... ..	44
Figure B.1 – Illustration of a simple E-field sensor, together with its Norton equivalent circuit.....	46
Figure B.2 – Magnitude and phase of the normalized frequency function $\hat{F}(\omega\tau)$ for the field sensor.....	47
Figure B.3 – Illustration of a simple B-field sensor, together with its Thevenin equivalent circuit.....	49
Figure B.4 – Illustration of an E-field sensor over a ground plane used for measuring the vertical electric field, or equivalently, the surface charge density.....	50
Figure B.5 – Illustration of the half-loop B-dot sensor used for measuring the tangential magnetic field, or equivalently, the surface current density.....	52
Figure B.6 – Simplified concept for measuring wire currents.....	53
Figure B.7 – Construction details of a current sensor.....	54
Figure B.8 – Example of the measured sensor impedance magnitude of a nominal 1 $\Omega$ current sensor.....	55
Figure B.9 – Geometry of the inclined I-dot current sensor.....	55
Figure B.10 – Design concept for a coaxial cable current sensor.....	56
Figure B.11 – Shape and dimensions of a CIP-10 coaxial cable current sensor.....	57
Figure B.12 – Configuration of a coaxial cable I-dot current sensor.....	57
Figure D.1 – Voltage and current relationships for a general two-port network.....	62
Figure D.2 – Voltage and current definitions for the chain parameters.....	63
Figure D.3 – Cascaded two-port networks.....	64
Figure D.4 – Representation of the of a simple measurement chain using the chain parameter matrices.....	64
Figure D.5 – Simple equivalent circuit for the measurement chain.....	65
Figure D.6 – A simple two-port network modelled by chain parameters.....	65
Table A.1 – Examples of time waveform p-norms.....	42
Table A.2 – Time waveform norms used for high-power transient waveforms.....	42
Table D.1 – Chain parameters for simple circuit elements.....	66

INTERNATIONAL ELECTROTECHNICAL COMMISSION

**ELECTROMAGNETIC COMPATIBILITY (EMC) –**

**Part 4-33: Testing and measurement techniques –  
Measurement methods for high-power transient parameters**

FOREWORD

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International Standard IEC 61000-4-33 has been prepared by subcommittee 77C: High power transient phenomena, of IEC technical committee 77: Electromagnetic compatibility.

It has the status of a basic EMC publication in accordance with IEC Guide 107.

The text of this standard is based on the following documents:

FDIS	Report on voting
77C/156/FDIS	77C/160/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

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## INTRODUCTION

IEC 61000 is published in separate parts according to the following structure:

### **Part 1: General**

General considerations (introduction, fundamental principles)

Definitions, terminology

### **Part 2: Environment**

Description of the environment

Classification of the environment

Compatibility levels

### **Part 3: Limits**

Emission limits

Immunity limits (in so far as they do not fall under the responsibility of the product committees)

### **Part 4: Testing and measurement techniques**

Measurement techniques

Testing techniques

### **Part 5: Installation and mitigation guidelines**

Installation guidelines

Mitigation methods and devices

### **Part 6: Generic standards**

### **Part 9: Miscellaneous**

Each part is further subdivided into several parts and published either as International Standards or as technical specifications or technical reports, some of which have already been published as sections. Others will be published with the part number followed by a dash and a second number denoting the subdivision (example: 61000-6-1).

## ELECTROMAGNETIC COMPATIBILITY (EMC) –

### Part 4-33: Testing and measurement techniques – Measurement methods for high-power transient parameters

#### 1 Scope

This part of IEC 61000 provides a basic description of the methods and means (e.g., instrumentation) for measuring responses arising from high-power transient electromagnetic parameters. These responses can include:

- the electric ( $E$ ) and/or magnetic ( $H$ ) fields (e.g., incident fields or incident plus scattered fields within a system under test);
- the current  $I$  (e.g., induced by a transient field or within a system under test);
- the voltage  $V$  (e.g., induced by a transient field or within a system under test);
- the charge  $Q$  induced on a cable or other conductor.

NOTE The charge  $Q$  on the conductor is a fundamental quantity that can be defined at any frequency. The voltage  $V$ , however, is a defined (e.g., secondary) quantity, which is valid only at low frequencies. At high frequencies, the voltage cannot be defined as the line integral of the E-field, since this integral is path-dependent. Thus, for very fast rising pulses (having a large high-frequency spectral content) the use of the voltage as a measurement observable is not valid. In this case, the charge is the desired quantity to be measured.

These measured quantities are generally complicated, time-dependent waveforms, which can be described approximately by several scalar parameters, or “observables”. These parameters include:

- the peak amplitude of the response,
- the waveform rise-time,
- the waveform fall-time (or duration)
- the pulse width, and
- mathematically defined norms obtained from the waveform.

This International Standard provides information on the measurement of these waveforms and on the mathematical determination of the characterizing parameters. It does not provide information on specific level requirements for testing.

#### 2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60050-161, *International Electrotechnical Vocabulary (IEV) – Chapter 161: Electromagnetic compatibility*

IEC 61000-2-9, *Electromagnetic compatibility (EMC) – Part 2: Environment – Section 9: Description of HEMP environment – Radiated disturbance*

IEC 61000-2-10, *Electromagnetic compatibility (EMC) – Part 2-10: Environment – Description of HEMP environment – Conducted disturbance*

IEC 61000-4-20, *Electromagnetic compatibility (EMC) – Part 4-20: Testing and measurement techniques – Emission and immunity testing in transverse electromagnetic (TEM) waveguides*

IEC 61000-4-23, *Electromagnetic compatibility (EMC) – Part 4-23: Testing and measurement techniques – Test methods for protective devices for HPEM and other radiated disturbances*

IEC 61000-4-25, *Electromagnetic compatibility (EMC) – Part 4-25: Testing and measurement techniques – HEMP immunity test methods for equipment and systems*

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